



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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企业微信二维码



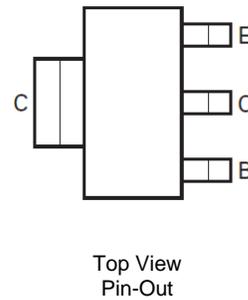
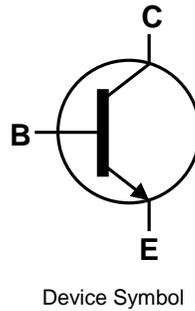
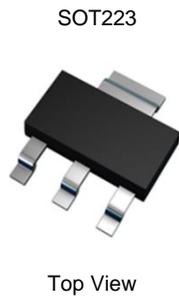
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## Features

- $BV_{CEO} > 150V$
- $I_C = 5A$  High Continuous Collector Current
- $I_{CM} = 10A$  Peak Pulse Current
- Very Low Saturation Voltage  $V_{CE(sat)} < 110mV @ 1A$
- $R_{CE(sat)} = 50m\Omega$  for a Low Equivalent On-Resistance
- $h_{FE}$  Specified Up to 10A for a High Gain Hold-Up

## Mechanical Data

- Package: SOT223
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 
- Weight: 0.112 grams (Approximate)



**Absolute Maximum Ratings** (@  $T_A = +25^{\circ}\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CB0}$	250	V
Collector-Emitter Voltage	$V_{CEO}$	150	V
Emitter-Base Voltage	$V_{EBO}$	7	V
Continuous Collector Current	$I_C$	5	A
Peak Pulse Current	$I_{CM}$	10	A
Base Current	$I_B$	1	A

**Thermal Characteristics** (@  $T_A = +25^{\circ}\text{C}$ , unless otherwise specified.)

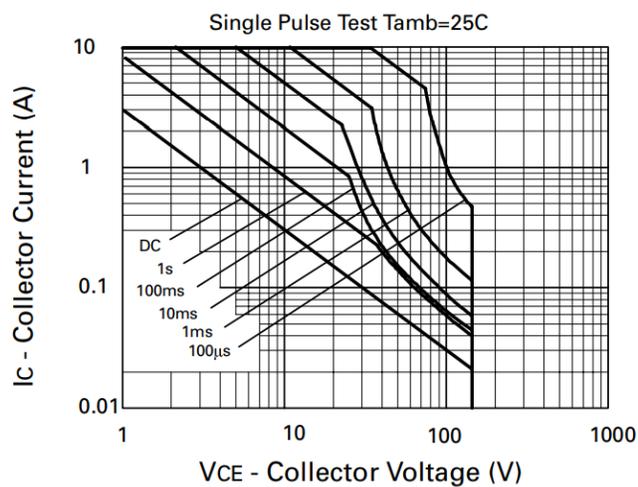
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	$P_D$	3.0	W
		24	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	1.6	mW/ $^{\circ}\text{C}$
		12.8	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$
		78	
Thermal Resistance Junction to Lead	$R_{\theta JL}$	8.8	$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^{\circ}\text{C}$

**ESD Ratings** (Note 8)

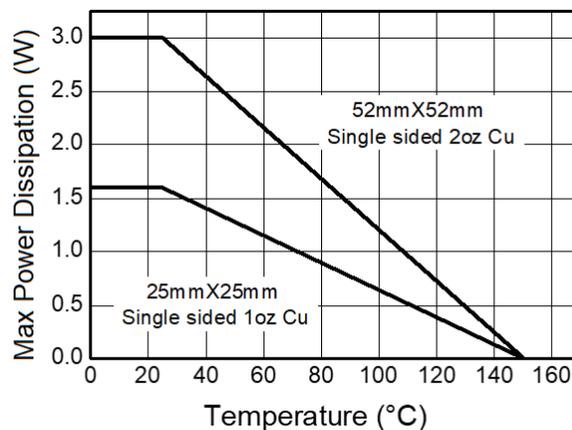
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device surface mounted on 52mm X 52mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; device measured when operating in steady state condition.
  6. Same as Note 5, except the device is mounted on 25mm x 25mm single sided 1oz weight copper.
  7. Thermal resistance from junction to solder-point (at the end of the collector lead).
  8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

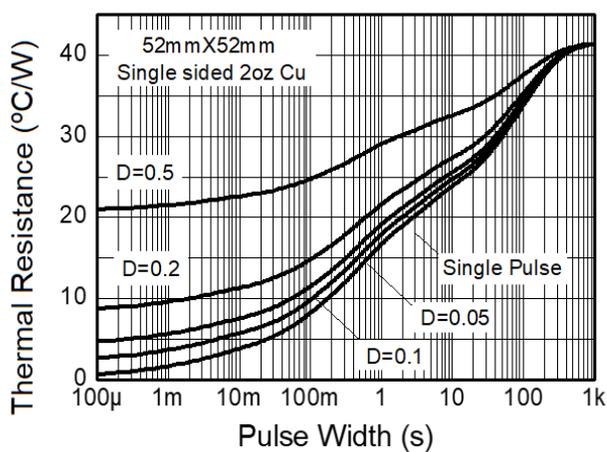
## Thermal Characteristics and Derating Information



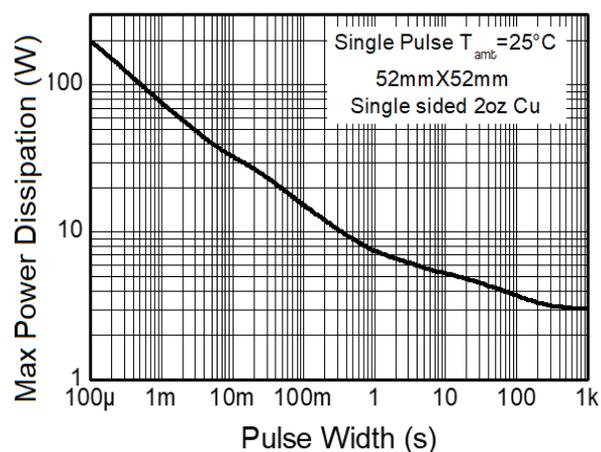
**Fig. 1 Safe Operating Area**



**Fig.2 Derating Curve**



**Fig.3 Transient Thermal Impedance**



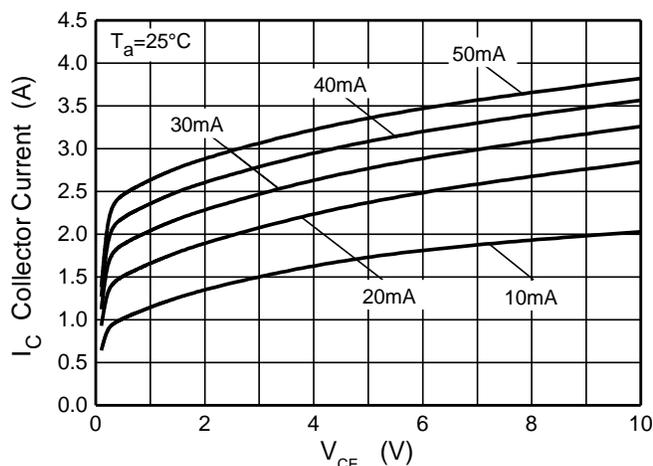
**Fig.4 Pulse Power Dissipation**

**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

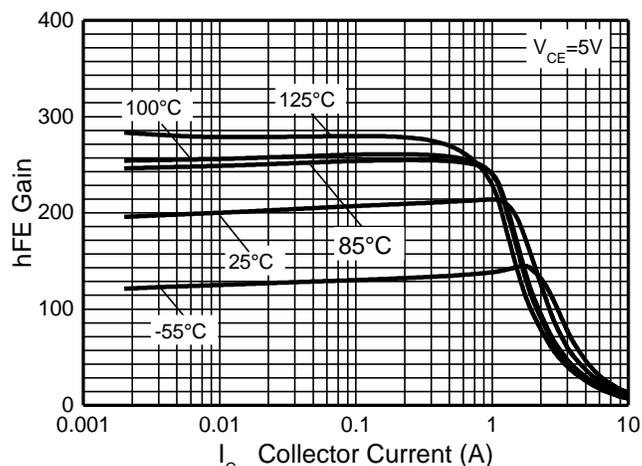
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	250	375	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage	$BV_{CER}$	250	375	—	V	$I_C = 1\mu\text{A}, R_B \leq 1\text{k}\Omega$
Collector-Emitter Breakdown Voltage (Note 9)	$BV_{CEO}$	150	180	—	V	$I_C = 1\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	7	8	—	V	$I_E = 100\mu\text{A}$
Collector Cut-Off Current	$I_{CBO}$	—	—	50 1	nA $\mu\text{A}$	$V_{CB} = 200\text{V}$ $V_{CB} = 200\text{V}, @T_A = +100^\circ\text{C}$
Collector Cut-Off Current	$I_{CER}$	—	—	50 1	nA $\mu\text{A}$	$V_{CE} = 200\text{V}, R \leq 1\text{k}\Omega$ $V_{CE} = 200\text{V}, R \leq 1\text{k}\Omega,$ $@T_A = +100^\circ\text{C}$
Emitter Cut-Off Current	$I_{EBO}$	—	—	10	nA	$V_{EB} = 6\text{V}$
Collector-Emitter Saturation Voltage (Note 9)	$V_{CE(sat)}$	—	20 35 60 250	40 65 110 355	mV	$I_C = 100\text{mA}, I_B = 5\text{mA}$ $I_C = 500\text{mA}, I_B = 50\text{mA}$ $I_C = 1\text{A}, I_B = 100\text{mA}$ $I_C = 5\text{A}, I_B = 500\text{mA}$
Base-Emitter Saturation Voltage (Note 9)	$V_{BE(sat)}$	—	—	1,250	mV	$I_C = 5\text{A}, I_B = 500\text{mA}$
Base-Emitter Turn-On Voltage (Note 9)	$V_{BE(on)}$	—	—	1,100	mV	$I_C = 5\text{A}, V_{CE} = 5\text{V}$
DC Current Gain (Note 9)	$h_{FE}$	100 100 15 —	200 200 30 10	— 300 — —	—	$I_C = 10\text{mA}, V_{CE} = 5\text{V}$ $I_C = 1\text{A}, V_{CE} = 5\text{V}$ $I_C = 5\text{A}, V_{CE} = 5\text{V}$ $I_C = 10\text{A}, V_{CE} = 5\text{V}$
Current Gain-Bandwidth Product (Note 9)	$f_T$	—	90	—	MHz	$V_{CE} = 10\text{V}, I_C = 100\text{mA}$ $f = 50\text{MHz}$
Output Capacitance	$C_{obo}$	—	22	—	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Switching Times	$t_{on}$ $t_{off}$	—	66 2,130	—	ns ns	$I_C = 1\text{A}, V_{CC} = 50\text{V}$ $I_{B1} = -I_{B2} = 100\text{mA}$

 Note: 9. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

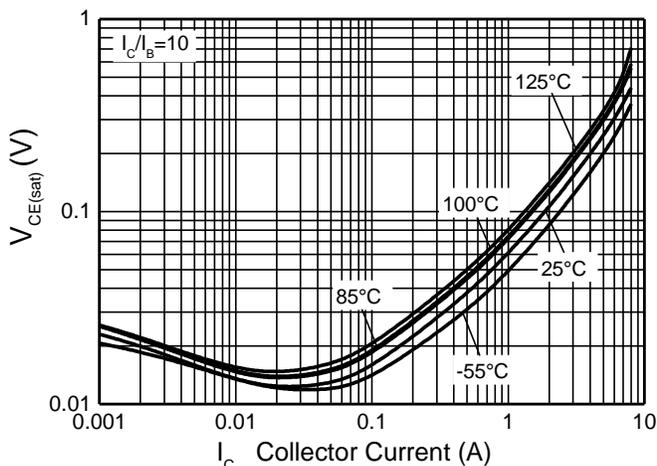
**Typical Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



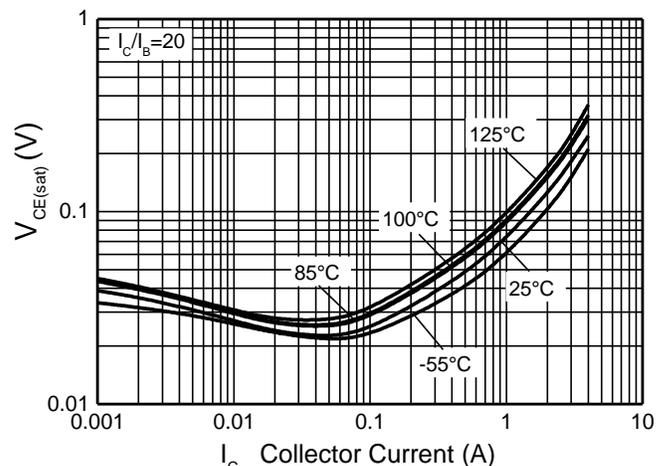
**Fig. 5**  $I_C$  v  $V_{CE}$



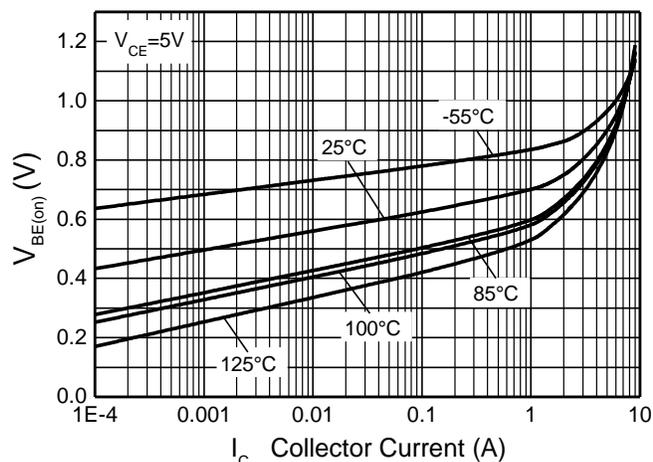
**Fig. 6**  $h_{FE}$  v  $I_C$



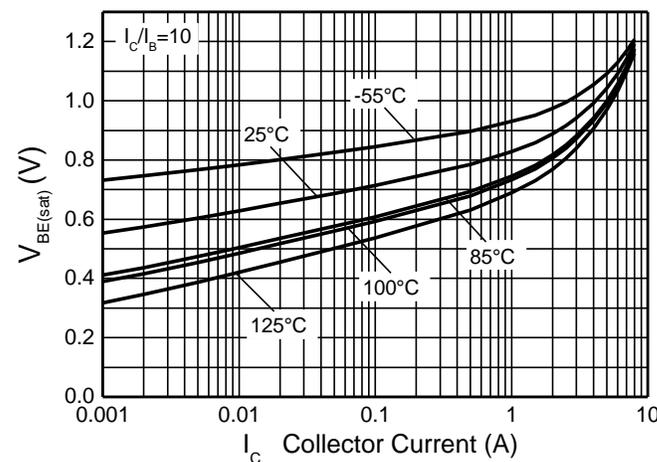
**Fig. 7**  $V_{CE(sat)}$  v  $I_C$



**Fig. 8**  $V_{CE(sat)}$  v  $I_C$

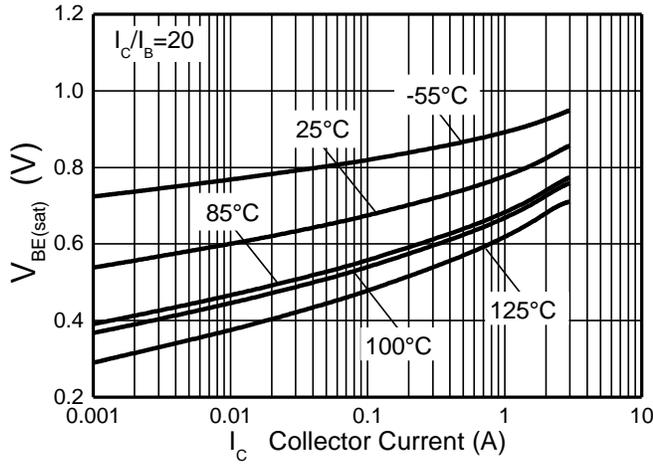


**Fig. 9**  $V_{BE(on)}$  v  $I_C$

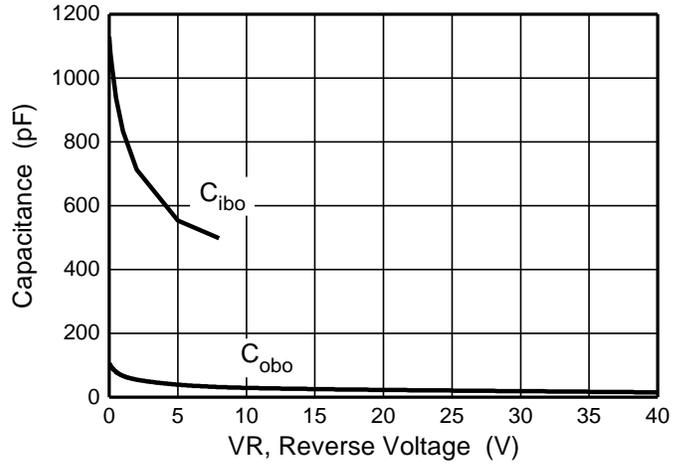


**Fig. 10**  $V_{BE(sat)}$  v  $I_C$

**Typical Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



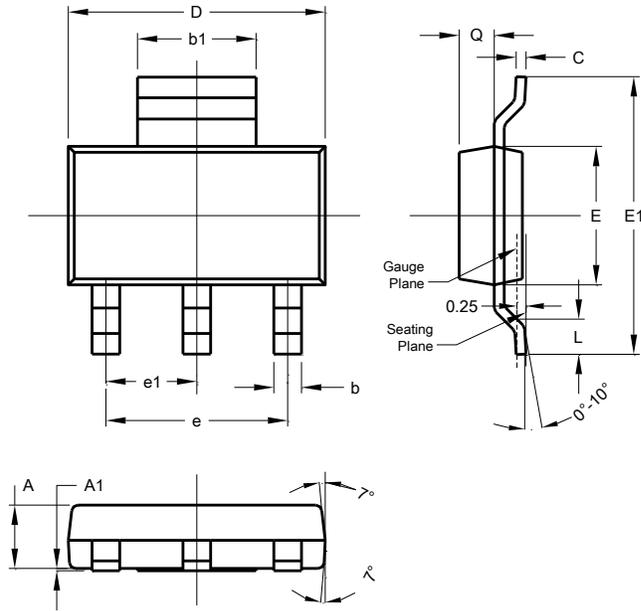
**Fig. 11**  $V_{BE(sat)} \text{ v } I_C$



**Fig. 12** Typical Junction Capacitance

**Package Outline Dimensions**

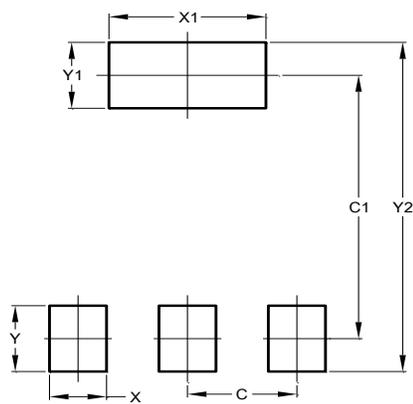
**SOT223**



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

**Suggested Pad Layout**

**SOT223**



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00